

SMT Solderball MGS adapter series

From 0.8 up to 1.27 mm pitch

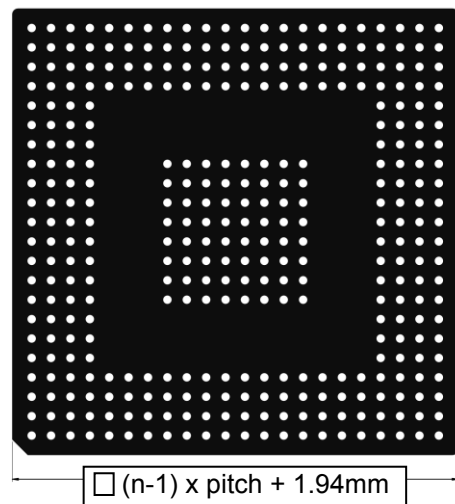
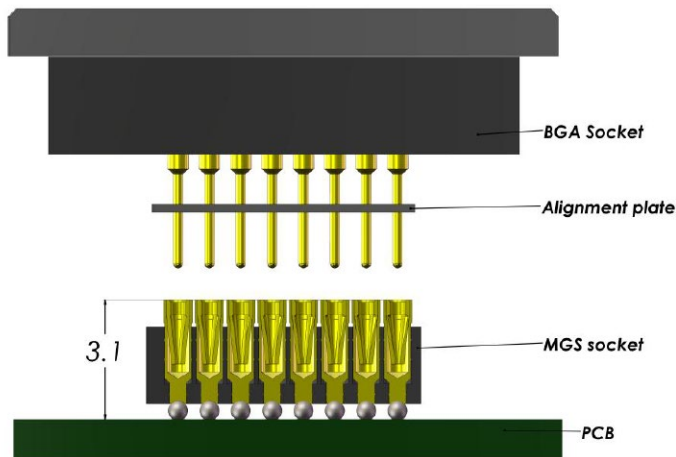


The E-tec Interconnect SMT Solderball MGS adapter emulates the package footprint and is easily installed using standard flux and reflow techniques. The solder ball adapters have the same solder ball types as the package's they are emulating. You can combine the SMT foot with any of the E-tec Test socket styles shown in the Test Socket catalogue. The Test Socket is plugged into these adapter, which will be delivered with gold plated through hole pin and alignment plate for easy insertion. We offer any pin-out, configuration and grid size for pitch 0.8mm, 1.00mm and 1.27mm.



Test Socket
(Plugged into adapter)

Solderball SMT Adapter



Specifications

Insulator (Adapter Wafer)	Material: Polyepoxy or equivalent high temp material
Contact (Terminal & Contact Clip)	Material: Terminal CuZn Contact Clip BeCu
Solderball	Material: Sn63Pb 37 (NON RoHS compliant) Sn96.5 Ag 3.0 Cu 0.5
Operating Temperature: -55°C to +125°C Processing Temperature: 260°C for 60 sec. Insertion force: 0.45N/Contact Extraction force: 0.25N/Contact	

How to order

MGS #### - SB01 - ### # 5 ##

